



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2827

Application No.: 09/486,556

Examiner: I. Patel

Filed: February 29, 2000

Docket No.: 105029

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE THEREOF,  
CIRCUIT BOARD AND ELECTRONIC INSTRUMENT

**AMENDMENT**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the November 6, 2002 Office Action, the shortened statutory period for response having been extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please replace claims 30, 50, 68 and 74 as follows:

30. (Amended) A method of manufacturing a semiconductor device, comprising:
- mounting a semiconductor chip on a substrate, said semiconductor chip having electrodes, said substrate having an interconnect pattern formed thereof and a protective layer covering at least a part of said interconnect pattern, said semiconductor chip mounted on said substrate such that an edge of said semiconductor chip does not overlap with said protective layer;
- electrically connecting said electrodes to said interconnect pattern; and
- adhering said semiconductor chip to said substrate by an adhesive, said adhesive